



A1N:50.XXJ

VOLTAGE RATINGS

Part Number	V_{RRM} , V_R (V)		V_{RSM} , V_R (V)	Max. non-rep. peak reverse voltage
	Max. rep. peak reverse voltage			
	T _J = 0 to 125°C	T _J = -40 to 0°C	T _J = 25 to 125°C	
A1N:50.02J	200	200	300	
A1N:50.04J	400	400	500	
A1N:50.06J	600	600	700	
A1N:50.08J	800	800	900	
A1N:50.10J	1000	1000	1100	
A1N:50.12J	1200	1200	1300	
A1N:50.14J	1400	1330	1500	
A1N:50.16J	1600	1520	1700	

This datasheet applies to:

Metric thread: A1N:50.XXJ

Inch thread: A2N:50.XXJ

MAXIMUM ALLOWABLE RATINGS

PARAMETER	VALUE	UNITS	NOTES
T _J Junction Temperature	-40 to 125	°C	-
T _{stg} Storage Temperature	-40 to 150	°C	-
I _{F(AV)} Max. Av. current @ Max. T _C	50 85	A °C	180° half sine wave
I _{F(RMS)} Nom. RMS current	80	A	-
I _{FSM} Max. Peak non-rep. surge current	1.18 1.29 1.37 1.49	kA	50 Hz half cycle sine wave 60 Hz half cycle sine wave 50 Hz half cycle sine wave 60 Hz half cycle sine wave Initial T _J = 125°C, rated V _{RRM} applied after surge. Initial T _J = 125°C, no voltage applied after surge.
I ² t Max. I ² t capability	6.05 6.59 8.53 9.30	kA ² s	t = 10ms t = 8.3 ms t = 10ms t = 8.3 ms Initial T _J = 125°C, rated V _{RRM} applied after surge. Initial T _J = 125°C, no voltage applied after surge.
I ² t ^{1/2} Max. I ² t ^{1/2} capability	102	kA ² s ^{1/2}	Initial T _J = 125°C, no voltage applied after surge. I ² t for time t _x = I ² t ^{1/2} * t _x ^{1/2} . (0.1 < t _x < 10ms).
di/dt Max. Non-repetitive rate-of-rise current	150	A/ s	T _J = 125°C, V _D = V _{DRM} , I _{TM} = 1600A. Gate pulse: 20V, 20 , 10 s, 0.5 s rise time, Max. repetitive di/dt is approximately 40% of non-repetitive value.
P _{GM} Max. Peak gate power	8	W	tp < 5 ms
P _{G(AV)} Max. Av. gate power	2	W	-
+I _{GM} Max. Peak gate current	150	mA	tp < 5 ms
-V _{GM} Max. Peak negative gate voltage	2	V	-
F Mounting Force	2.8(25)	N.m(Lbf.in)	Non lubricated threads



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CHARACTERISTICS

PARAMETER	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
V_{TM} peak on-state voltage	---	---	1.68	V	Initial $T_J = 25^\circ C$, 50-60Hz half sine, $I_{peak} = 79A$.
$V_{T(TO)}$ Threshold voltage	---	---	0.85	V	$T_J = 125^\circ C$ Av. power = $V_{T(TO)} * I_{T(AV)} + r_T * [I_{T(RMS)}]^2$, 180 Half Sine.
r_T Slope resistance	---	---	4.6	m	Use low values for $I_{TM} <$ rated $I_{T(AV)}$
I_L Latching current	---	---	400	mA	$T_C = 125^\circ C$, 12V anode. Gate pulse: 10V, 20 , 100 s.
I_H Holding current	---	---	200	mA	$T_C = 25^\circ C$, 12V anode. Initial $I_T = 15A$.
t_d Delay time	---	0.7	0.9	s	$T_C = 25^\circ C$, $V_D = V_{DRM}$, 50A resistive load. Gate pulse: 10V, 20 , 10 s, 1 s rise time.
t_q Turn-off time	---	---	110	s	$T_J = 125^\circ C$, $I_{TM} = 500A$, $di/dt = 25A/ s$, $V_R = 50V$. $dv/dt = 20 V/ s$ lin. to rated V_{DRM} . Gate: 0V, 100 .
dv/dt Critical rate-of-rise of off-state voltage	---	---	500	V/ s	$T_J = 125^\circ C$, Exp. To 67% V_{DRM} , gate open.
I_{RM} , I_{DM} Peak reverse and off-state current	---	10	15	mA	$T_J = 125^\circ C$, Rated V_{RRM} and V_{DRM} , gate open.
I_{GT} DC gate current to trigger	---	---	300	mA	$T_C = -40^\circ C$
	50	80	150		$T_C = 25^\circ C$ +12V anode-to-cathode. For recommended
V_{GT} DC gate voltage to trigger	5	---	---	V	$T_C = -40^\circ C$ gate drive see "Gate Characteristics" figure.
	2.5	---	---		$T_C = 25^\circ C$
V_{GD} DC gate voltage not to trigger	---	---	0.2	V	$T_C = 25^\circ C$, Max. Value which will not trigger with rated V_{DRM} anode.
R_{thJC} Thermal resistance, junction-to-case	---	---	0.35	°C/W	DC operation, single side cooled.
	---	---	0.41	°C/W	180° sine wave, single side cooled.
	---	---	0.46	°C/W	120° rectangular wave, single side cooled.
R_{thCS} Thermal resistance, case-to-sink	---	---	0.25	°C/W	Mtg. Surface smooth, flat and greased. Single side cooled.
wt Weight	---	28(1)	---	g(oz.)	---
Case Style	TO-208AC(TO-65)		JEDEC		---

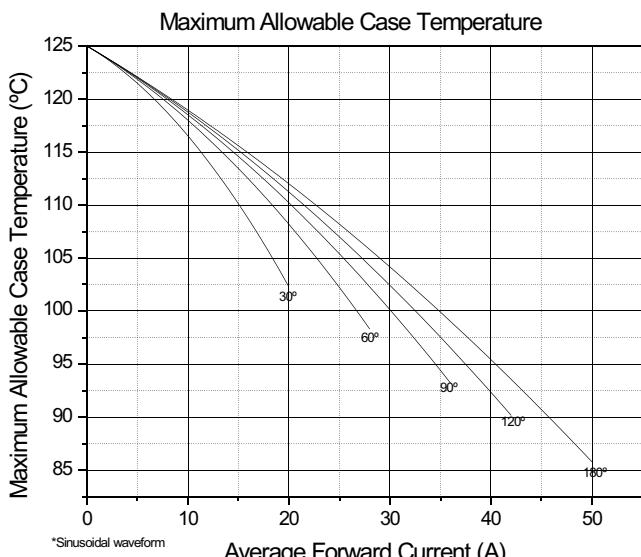


Fig. 1 - Current Ratings Characteristics

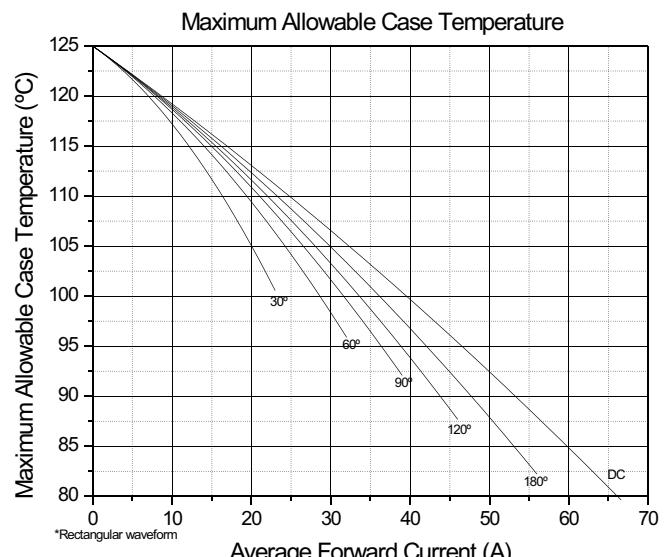


Fig. 2 - Current Ratings Characteristics



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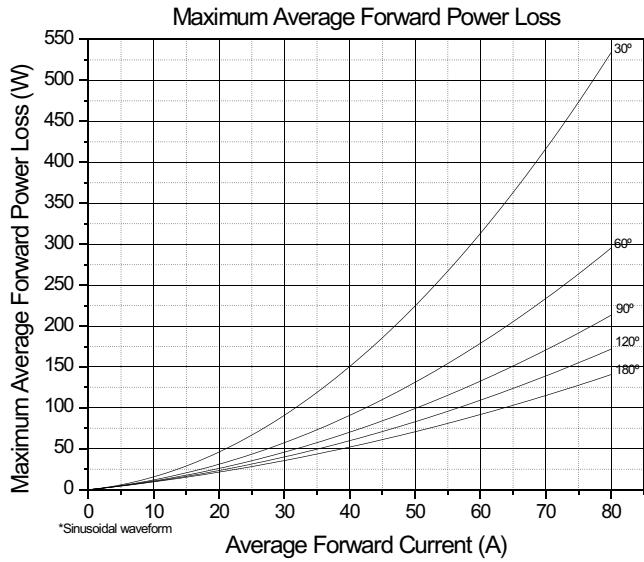


Fig. 3 - Forward Power Loss Characteristics

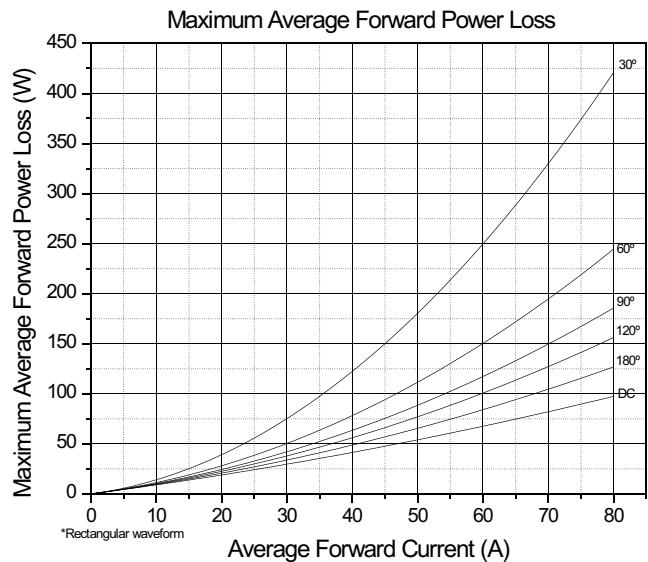


Fig. 4 - Forward Power Loss Characteristics

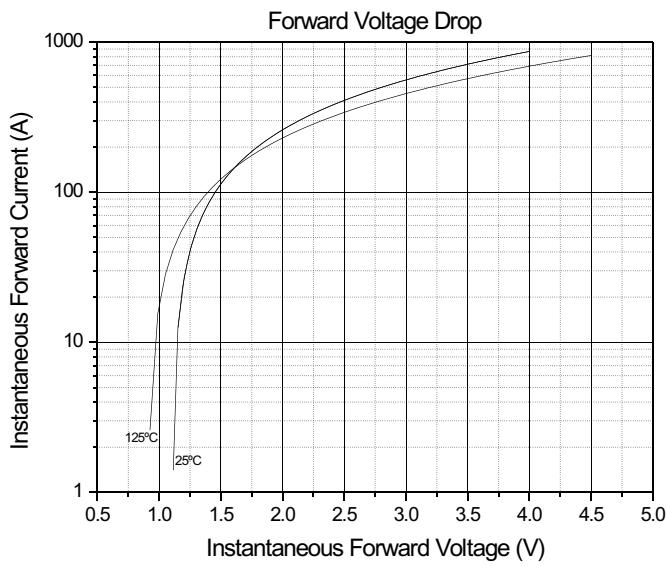


Fig. 5 - Forward Voltage Drop Characteristics

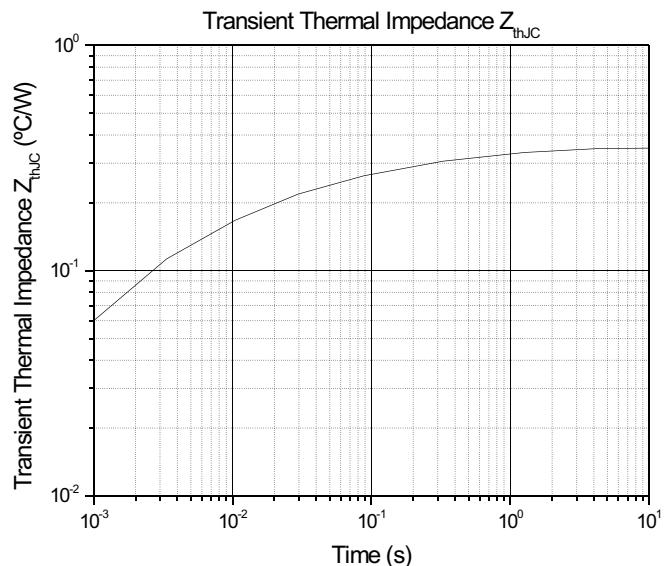


Fig. 6 - Transient Thermal Impedance Characteristics



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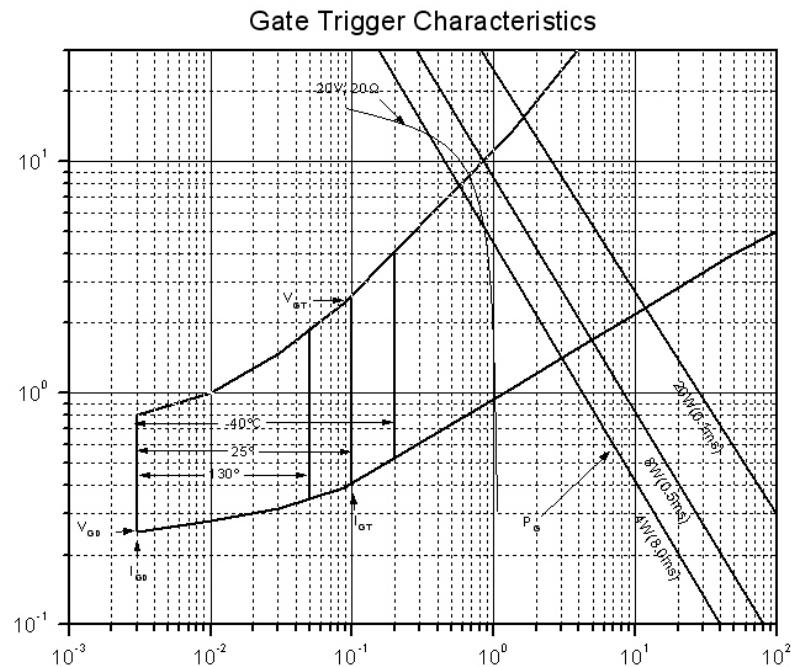


Fig. 7 - Gate Trigger Characteristics

TO-208AC (TO-65)

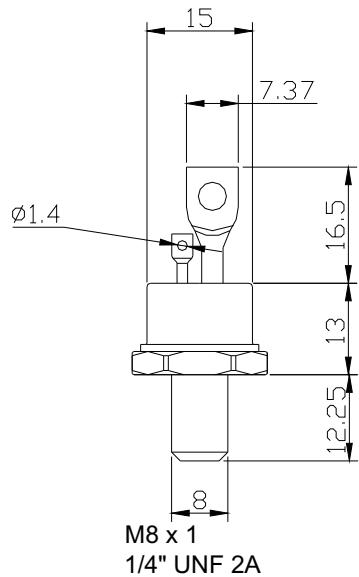


Fig. 8 - Outline Characteristics